

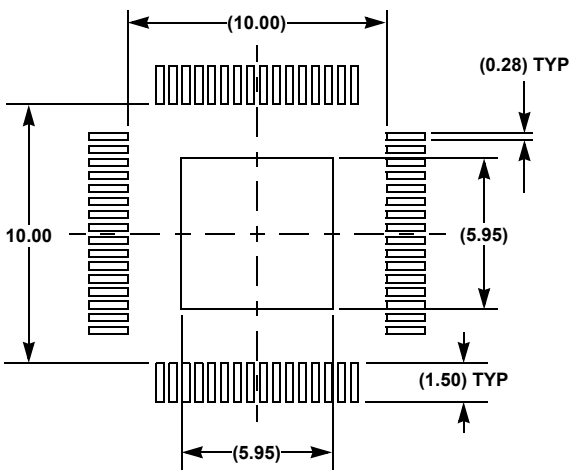
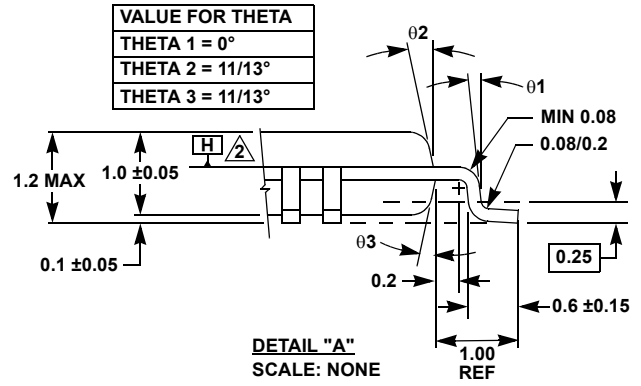
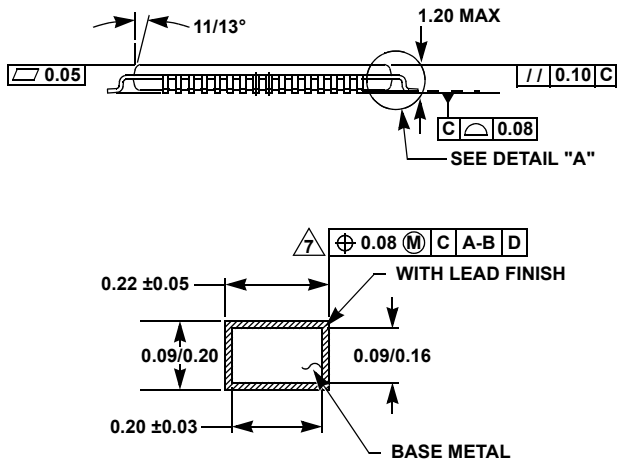
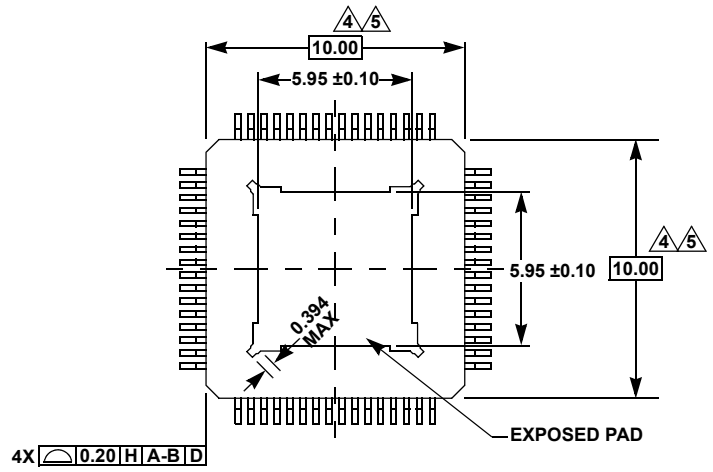
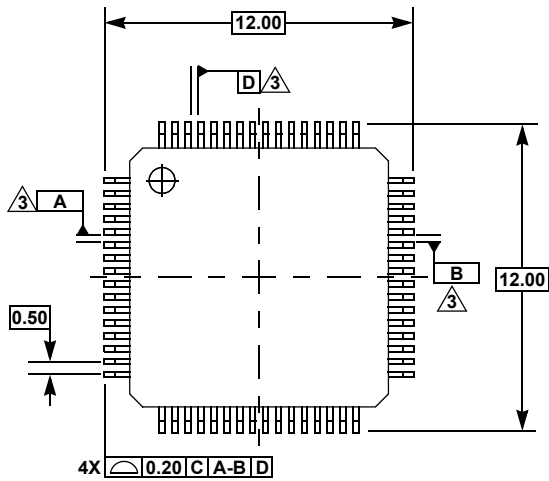
Plastic Packages for Integrated Circuits

Package Outline Drawing

Q64.10x10H

64 LEAD THIN PLASTIC QUAD FLATPACK PACKAGE WITH EXPOSED PAD (EP-TQFP)

Rev 0, 4/15



NOTES:

- All dimensioning and tolerancing conform to ANSI Y14.5-1982.
- Datum plane **H** located at mold parting line and coincident with lead, where lead exits plastic body at bottom of parting line.
- Datums **A-B** and **D** to be determined at centerline between leads where leads exit plastic body at datum plane **H**.
- Dimensions do not include mold protrusion. Allowable mold protrusion is 0.25mm. per side.
- These dimensions to be determined at datum plane **H**.
- Package top dimensions are smaller than bottom dimensions and top of package will not overhang bottom of package.
- Dimension **b** does not include dam bar protrusion. Allowable dam bar protrusion shall not cause the lead width to exceed the **b** dimension by more than 0.08mm. Dam bar cannot be located on the lower radius of the foot. Minimum space between protrusion and an adjacent lead is 0.07mm.
△ Exact shape of each corner is optional.
- Controlling dimension: millimeter.
- This outline conforms to JEDEC publication 95 registration MS-026, variation ACD.
- Dimensions in () are for reference only.